

Docket No. 213480USO

IN RE APPLICATION OF: Sei TSUNODA, et al.

SERIAL NO: 09/942,626

FILED: August 31, 2001

FOR: LOW DIELECTRIC CONSTANT MATERIALS HAVING THERMAL RESISTANCE, INSULATION FILM BETWEEN SEMICONDUCTOR LAYERS USING THE SAME, AND SEMICONDUCTOR DEVICE

COMMISSIONER FOR PATENTS  
ALEXANDRIA, VIRGINIA 22313



RESPONSE UNDER 37 CFR 1.116-  
EXPEDITED PROCEDURE EXAMINING  
GROUP 1751

SIR:

Transmitted herewith is an amendment in the above-identified application.

Corres. and Mail  
**BOX AF**

- ☒ No additional fee is required
- ☐ Small entity status of this application under 37 C.F.R. §1.9 and §1.27 is claimed.
- ☐ Additional documents filed herewith:

The Fee has been calculated as shown below:

CLAIMS	CLAIMS REMAINING		HIGHEST NUMBER PREVIOUSLY PAID	NO. EXTRA CLAIMS	RATE	CALCULATIONS
TOTAL	8	MINUS	20	0	x \$50 =	\$0.00
INDEPENDENT	5	MINUS	6	0	x \$200 =	\$0.00
		<input type="checkbox"/> MULTIPLE DEPENDENT CLAIMS				+ \$360 = \$0.00
		TOTAL OF ABOVE CALCULATIONS				\$0.00
		<input type="checkbox"/> Reduction by 50% for filing by Small Entity				\$0.00
		<input type="checkbox"/> Recordation of Assignment				+ \$40 = \$0.00
		TOTAL				\$0.00

- ☐ A check in the amount of \$0.00 is attached.
- ☐ Credit card payment form is attached to cover the fees in the amount of \$0.00
- ☒ Please charge any additional Fees for the papers being filed herewith and for which no check or credit card payment is enclosed herewith, or credit any overpayment to deposit Account No. 15-0030. A duplicate copy of this sheet is enclosed.
- ☒ If these papers are not considered timely filed by the Patent and Trademark Office, then a petition is hereby made under 37 C.F.R. §1.136, and any additional fees required under 37 C.F.R. §1.136 for any necessary extension of time may be charged to Deposit Account No. 15-0030. A duplicate copy of this sheet is enclosed.

OBLON, SPIVAK, McCLELLAND,  
MAIER & NEUSTADT, P.C.  
Norman E. Oblon

Harris A. Pitlick

Registration No. 38,779

Customer Number

**22850**

Tel. (703) 413-3000  
Fax. (703) 413-2220  
(OSMMN 05/03)



"RESPONSE UNDER 37 CFR 1.116-  
EXPEDITED PROCEDURE EXAMINING  
GROUP 1751"

DOCKET NO: 213480US0

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF :  
SEI TSUNODA, ET AL. : EXAMINER: HAMLIN, D. G.  
SERIAL NO: 09/942,626 :  
FILED: AUGUST 31, 2001 : GROUP ART UNIT: 1751  
FOR: LOW DIELECTRIC CONSTANT :  
MATERIAL HAVING THERMAL  
RESISTANCE, INSULATION FILM  
BETWEEN SEMICONDUCTOR LAYERS  
USING THE SAME, AND  
SEMICONDUCTOR DEVICE

AMENDMENT UNDER 37 CFR 1.116

COMMISSIONER FOR PATENTS  
ALEXANDRIA, VIRGINIA 22313

SIR:

Responsive to the Final Office Action dated November 19, 2004, Applicants respectfully request reconsideration of the above-identified application **and the finality of the Office Action**, in view of the following amendment and remarks.

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper.

**Discussion of the Amendment** begins on page 7 of this paper.

**Remarks** begin on page 8 of this paper.